

Highly doped p-type µc-Si through remote inductively coupled plasma assisted chemical vapour deposition (ICP-**CVD)** for photovoltaic passivation applications J. W. M. Lim<sup>\*</sup>, Y. Guo, S. Huang, L. Xu, S. Xu Plasma Sources and Applications Centre, NIE, Nanyang Technological University 1 Nanyang Walk, Singapore 637616 Institute of Physics (IPS) Meeting 2017



# Introduction



### **Experimental results**



with BSF passivation layer fabricated at PSAC

5. Enhanced minority carrier lifetime results in higher  $\eta_{eff}$  values





A low frequency R-ICP reactor couples 3000 W of RF power through a dielectric lid into a chamber filled with  $SiH_4+H_2+B_2H_6$  as feedstocks for film growth

**Experimental conditions** 

Water outlet	Process parameters					
Pothole cover	RF Power	3000 W				
-	Process time	15 minutes				
o vacuum pump	Substrate temperature	150 ⁰C				
	Pressure	2 Pa				
ottom plate	SiH <sub>4</sub> /H <sub>2</sub> mass flow ratio	1:10				
upply	B <sub>2</sub> H <sub>6</sub> flow rate	1 – 5 sccm				
	<u>_arge applied RF power</u> and <u>high H<sub>2</sub> dilution</u>					
<u>e</u>	ennances the crystallinity of the	nin tiims				



Dark conductivity and photo-response still remains high (device grade),  $\sigma_{ph} > 10^5$ 

Diborane Flowrate (sccm) **Figure 7**: **a.)** Evolution of film crystallinity as  $B_2H_6$  flow increases **b.)** Evolution of bulk concentration and mobility obtained through hall effect measurements as  $B_2H_6$  flow increases

### **Conclusion & further work**



Deterministic control of crystalline phase and doping concentration can be achieved through ICP-CVD with  $SiH_4+H_2+B_2H_6$ 

High quality "high-low" and p-n junctions demonstrated with fabricated films. Good PV response even without ARC and surface treatment Good prospects for TF PV cells/BSF applications

Work in progress: Incorporation with other plasma processes (texturing, ARC deposition, passivation) in tandem for fabrication of high efficiency PV cells Figure 8: I-V & PV characteristics of high-low junctions formed with µc-Si (B) and a p-type Si substrate

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# Introduction

Crystalline silicon based photovoltaic (PV) cells still remains as 1 of the most promising solutions to the global energy crisis by offering a renewable and low cost alternative to conventional fuels, which can be rapidly implemented in industry due to good understanding of silicon based optoelectronic devices driven by the technological revolution. However, efficiencies of c-Si still remain relatively low due to either optical losses (poor coupling of light into active layers), or electronic losses (recombination of photo-generated carriers). In this work, a remote ICP facility was used to fabricate highly doped (~10<sup>20</sup> cm<sup>-3</sup>) p-type µc-Si thin films through fragmentation and dissociation of SiH<sub>4</sub>+H<sub>2</sub>+B<sub>2</sub>H<sub>6</sub> feedstocks. The remote configuration of the discharge facility enabled low damage of fabricated films typically associated with ICP discharges, while retaining the uniform discharge characteristics over large areas with enhanced production of radicals and reactive species. This resulted in highly crystalline and highly doped Si films which has huge potential for applications in both c-Si and thin film PV cells as well as other optoelectronic devices.

The aim of this project was to fabricate highly doped p-type µc-Si thin films through ICP-CVD to serve as a back surface field (BSF) effect passivation layer in PV cells

8	Power	Bias	Flow rate	Pressure	Process time	Feedstock gas
	3.2kW	-750V	10sccm	2Pa	30 minutes	Silane

Samples were exposed to a high-density silane plasma discharge in electromagnetic (H/bright) mode for deposition of amorphous silicon thin films. The discharge conditions were kept constant for both sets of experiments, with the only variation being the dielectric top lids. The resulting films were characterized with Secondary Ion Mass Spectroscopy (SIMS) and Fourier-transform Infra-red spectrocsopy (FTIR) to reveal the grades of the film and how the lids influence the ability of the reactor to stay free from contaminants.

Figure 8: Plasma processing parameters which were kept constant for film growth *Figure 9*: ToF (time of flight) Secondary Ion Mass Spectrometer (SIMS) Figure 10: Fourier-Transform Infra-red spectrometer (FTIR)



### **Experimental results**

Effect of dielectric lids on oxygen content in deposited thin films







5

500

700

800

600

Wavelenth (nm)



$$\varepsilon_p = 1 - \omega_{pe}^2 / [\omega(\omega + iv_{eff})]$$
$$\mathsf{P}_{\mathsf{p}} = \mathsf{d}_{\mathsf{t}}\varepsilon_{\mathsf{e}}$$

$$U_p^H = -\frac{i\omega r^2}{4} \sum_{n=1}^{\infty} \frac{[J_2(p_{1n})I_c\alpha_{1n})^2 \tanh(\gamma_n^p L)}{\cosh^2(\gamma_n^p d)(D_n^p)^2}$$

Figure 11: SIMS results showing the reduced oxygen content in films deposited with  $AI_2O_3$ dielectric lids, and improved deposition rates Figure 12: FTIR results showing the decreased peaks corresponding to Si-O bonding in samples deposited with  $AI_2O_3$  lids

- Reduction in measured absolute oxygen content in a-Si thin films fabricated with Al<sub>2</sub>O<sub>3</sub> top lid
- Peaks in IR spectra which correspond to Si-O bonding were less pronounced in samples which were fabricated with the Al<sub>2</sub>O<sub>3</sub> top lid
- Deposition rate increased drastically with the Al<sub>2</sub>O<sub>3</sub> top lid
- Experimental results concur with theoretical calculations and simulations
- Al<sub>2</sub>O<sub>3</sub> has a dielectric constant of 9.34 while SiO<sub>2</sub> has a dielectric constant of 4.41
- Value for dielectric constant contributes significantly to power delivered to and absorbed by plasma explaining the increase in deposition rate.
- More energy is required to sputter oxygenated species from  $AI_2O_3$  as compared to  $SiO_2$ accounting for lowered contaminant contents detected in films





Figure 4: Sample corresponding to oxygen undergoing HD-PIII with contaminants in a nitrogen Nitrogen plasma plasma discharge

### discharged in H-mode **Experimental methods**



Amorphous hydrogenated silicon was deposited on top of c-Si substrates in a LF-ICP reactor. Experiments were conducted with the conventional quartz (SiO<sub>2</sub>) lid first, before the lid was swapped out to alumina  $(Al_2O_3)$ . The reactor was evacuated to 10<sup>-4</sup> Pa prior to each experiment with the aid of a turbomolecular pump.

has shown promising applications in fabrication of device grade photovoltaic modules in plasma reactors. Apart from reducing oxygen contaminant species, the deposition rate was also seen to increase with the mentioned modifications. High quality contaminant free films are required for high efficiency PV cells. Dry processing in plasma reactors gives added control over the processes by tuning plasma parameters. Further work investigates the passivating qualitites of films by measuring the carrier lifetime. Light management issues are also dealt with in the process.

Figure 13/14: Graphs showing promising increment in carrier lifetime in films deposited with a-Si Figure 15: Modified CCP reactor texturing c-Si wafers with plasma etching

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